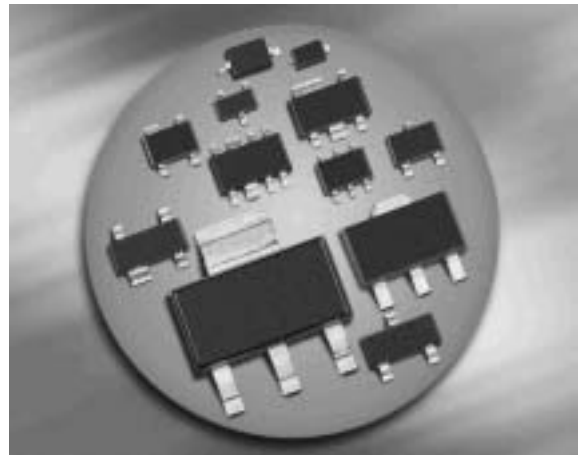
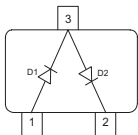


Silicon Switching Diode

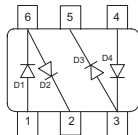
- For high-speed switching applications
- Series pair configuration
- BAV99S / U: For orientation in reel see package information below
- Pb-free (RoHS compliant) package¹⁾
- Qualified according AEC Q101



BAV99 BAV99W



BAV99S BAV99U



Type	Package	Configuration	Marking
BAV99	SOT23	series	A7s
BAV99S	SOT363	dual series	A7s
BAV99U	SC74	dual series	A7s
BAV99W	SOT323	series	A7s

¹⁾Pb-containing package may be available upon special request

Maximum Ratings at $T_A = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Value	Unit
Diode reverse voltage	V_R	80	V
Peak reverse voltage	V_{RM}	85	
Forward current	I_F	200	mA
Non-repetitive peak surge forward current	I_{FSM}		A
$t = 1 \mu\text{s}$		4.5	
$t = 1 \text{ ms}$		1	
$t = 1 \text{ s, single}$		0.5	
$t = 1 \text{ s, double}$		0.75	
Total power dissipation	P_{tot}		mW
BAV99, $T_S \leq 28^\circ\text{C}$		330	
BAV99S, $T_S \leq 85^\circ\text{C}$		250	
BAV99U, $T_S \leq 113^\circ\text{C}$		250	
BAV99W, $T_S \leq 110^\circ\text{C}$		250	
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-65 ... 150	

Thermal Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point ¹⁾	R_{thJS}		K/W
BAV99		≤ 360	
BAV99S		≤ 260	
BAV99U		≤ 150	
BAV99W		≤ 160	

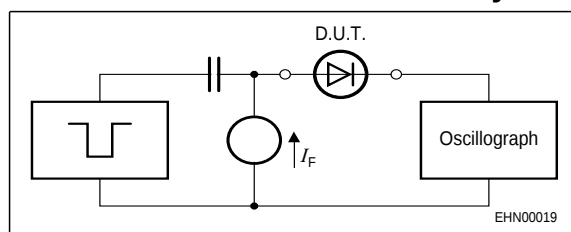
¹⁾For calculation of R_{thJA} please refer to Application Note Thermal Resistance

Electrical Characteristics at $T_A = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC Characteristics					
Breakdown voltage $I_{(BR)} = 100 \mu A$	$V_{(BR)}$	85	-	-	V
Reverse current $V_R = 70 V$ $V_R = 25 V, T_A = 150\text{ }^{\circ}C$ $V_R = 70 V, T_A = 150\text{ }^{\circ}C$	I_R	- - -	- - -	0.15 30 50	μA
Forward voltage $I_F = 1 mA$ $I_F = 10 mA$ $I_F = 50 mA$ $I_F = 100 mA$ $I_F = 150 mA$	V_F	- - - - -	- - - - -	715 855 1000 1200 1250	mV

Electrical Characteristics at $T_A = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
AC Characteristics					
Diode capacitance $V_R = 0\text{ V}$, $f = 1\text{ MHz}$	C_T	-	-	1.5	pF
Reverse recovery time $I_F = 10\text{ mA}$, $I_R = 10\text{ mA}$, measured at $I_R = 1\text{ mA}$, $R_L = 100\ \Omega$	t_{rr}	-	-	4	ns

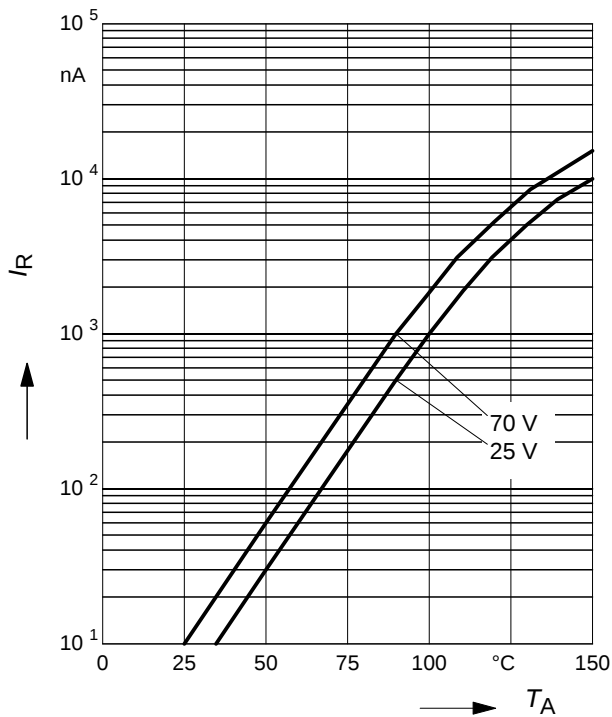
Test circuit for reverse recovery time


Pulse generator: $t_p = 100\text{ns}$, $D = 0.05$,
 $t_r = 0.6\text{ns}$, $R_i = 50\Omega$

Oscilloscope: $R = 50$, $t_r = 0.35\text{ns}$
 $C \leq 1\text{pF}$

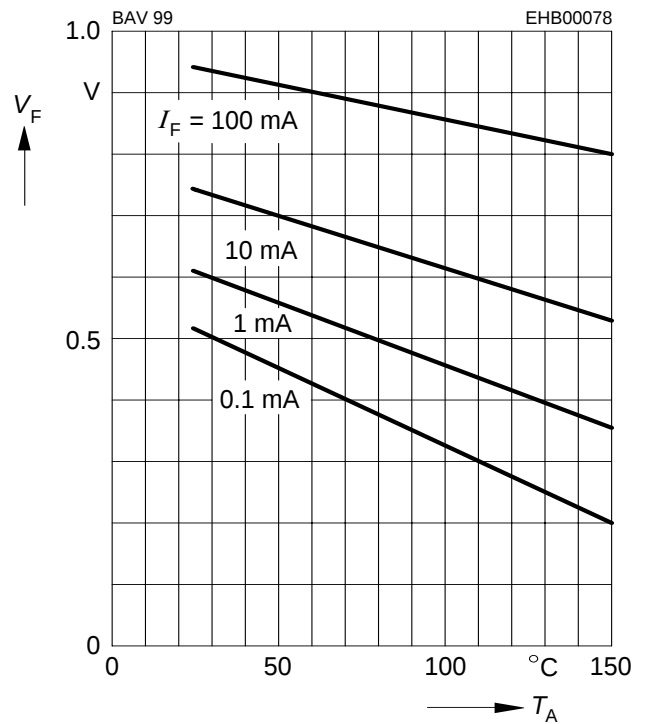
Reverse current $I_R = f(T_A)$

$V_R = \text{Parameter}$



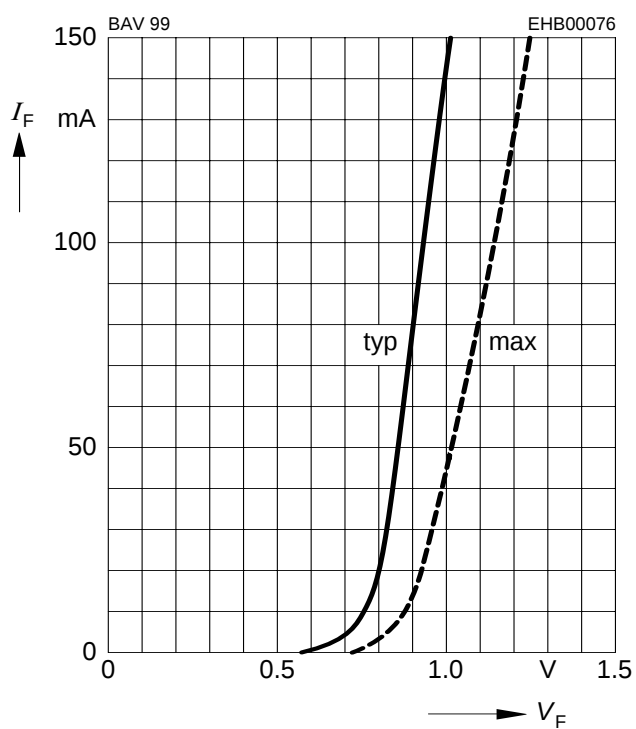
Forward Voltage $V_F = f(T_A)$

$I_F = \text{Parameter}$



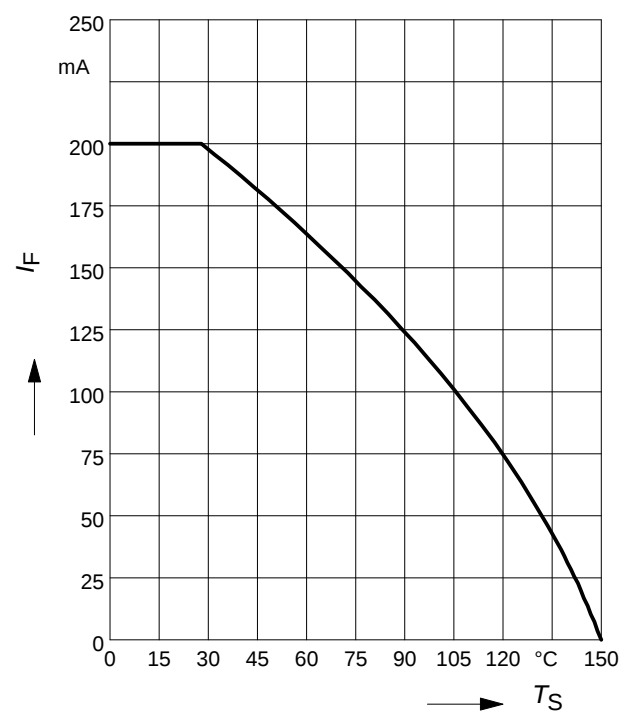
Forward current $I_F = f(V_F)$

$T_A = 25^\circ\text{C}$



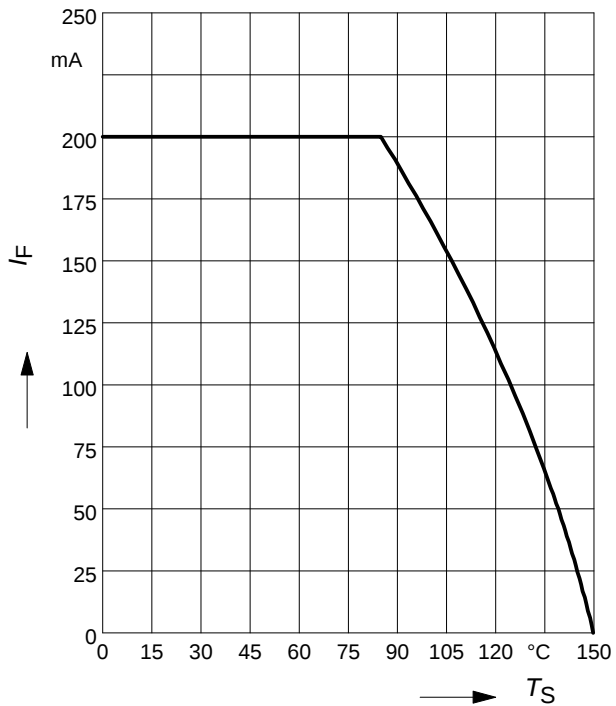
Forward current $I_F = f(T_S)$

BAV99



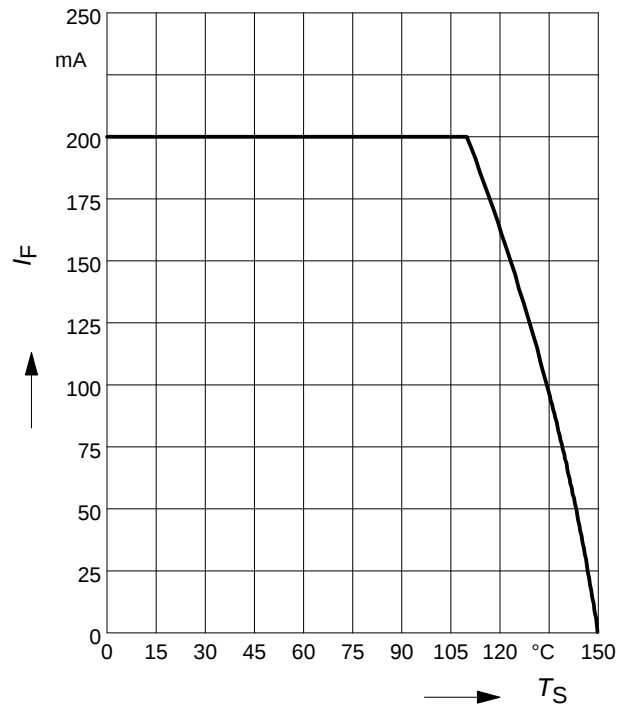
Forward current $I_F = f(T_S)$

BAV99S



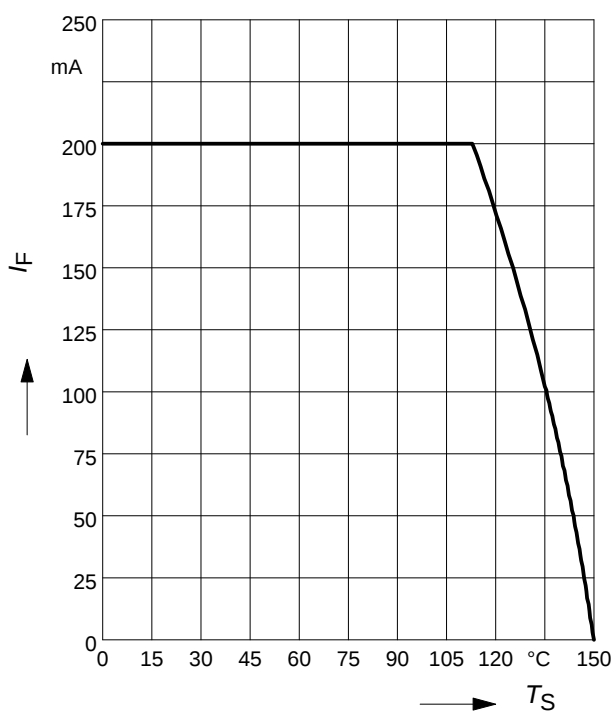
Forward current $I_F = f(T_S)$

BAV99U



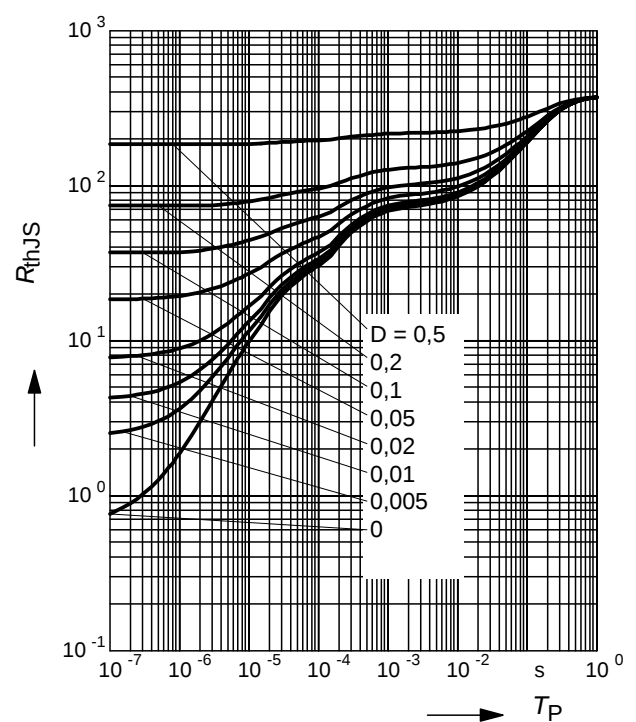
Forward current $I_F = f(T_S)$

BAV99W



Permissible Puls Load $R_{thJS} = f(t_p)$

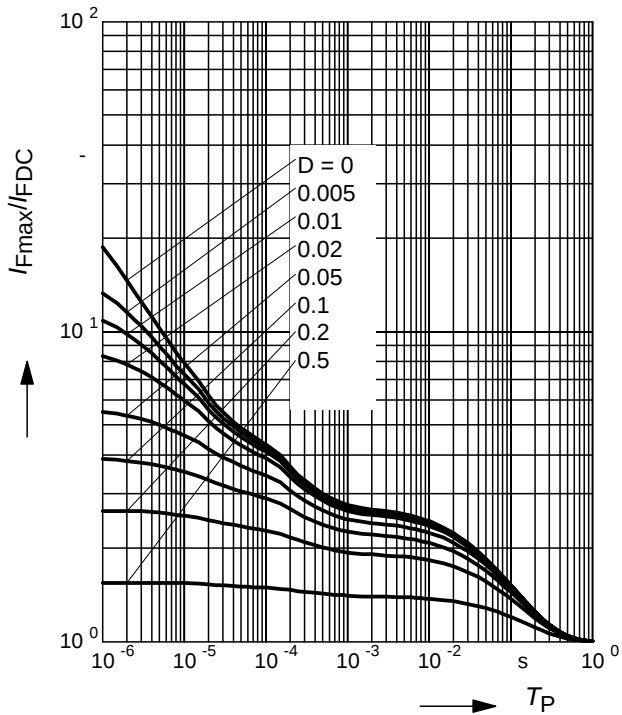
BAV99



Permissible Pulse Load

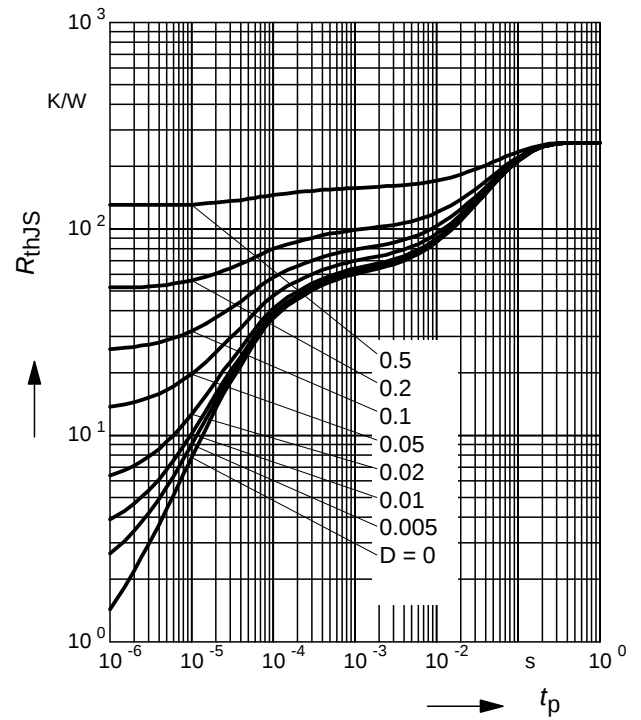
$$I_{Fmax}/I_{FDC} = f(t_p)$$

BAV99



Permissible Puls Load $R_{thJS} = f(t_p)$

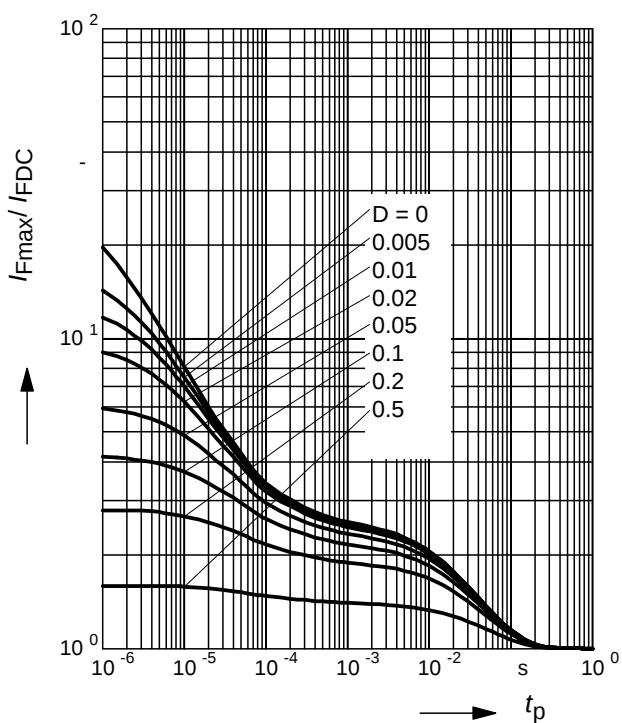
BAV99S



Permissible Pulse Load

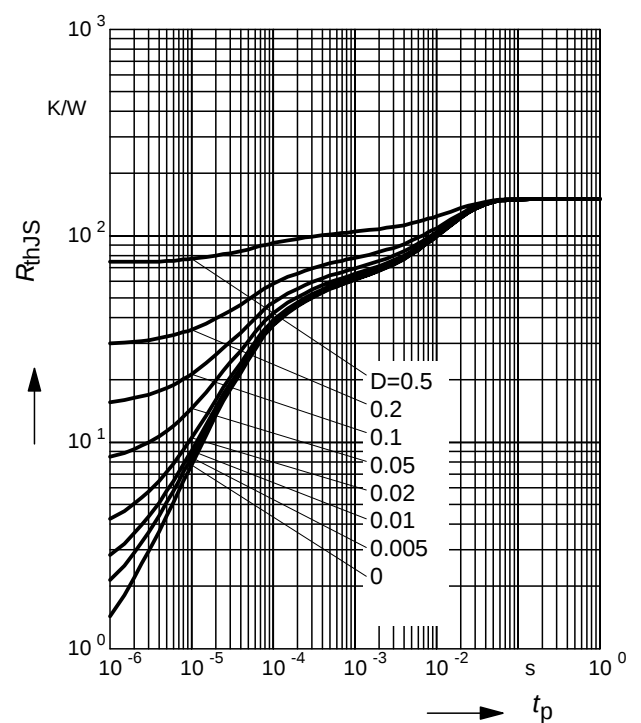
$$I_{Fmax}/I_{FDC} = f(t_p)$$

BAV99S



Permissible Puls Load $R_{thJS} = f(t_p)$

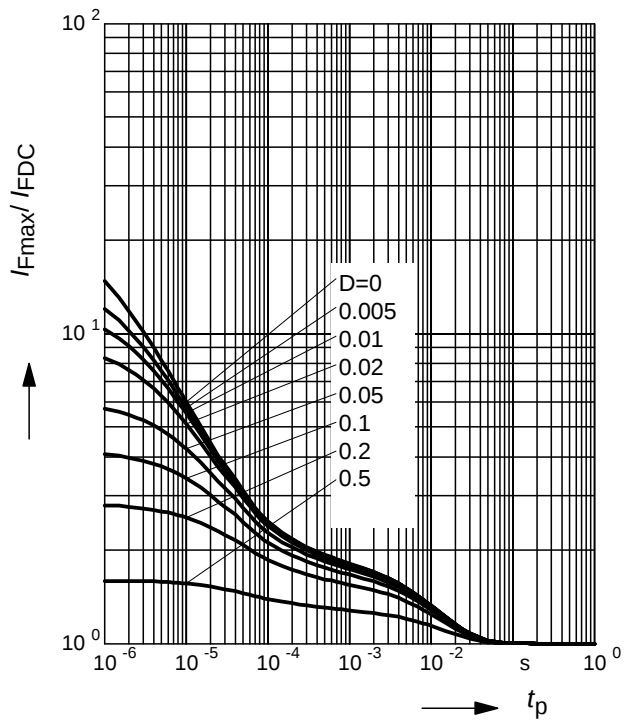
BAV99U



Permissible Pulse Load

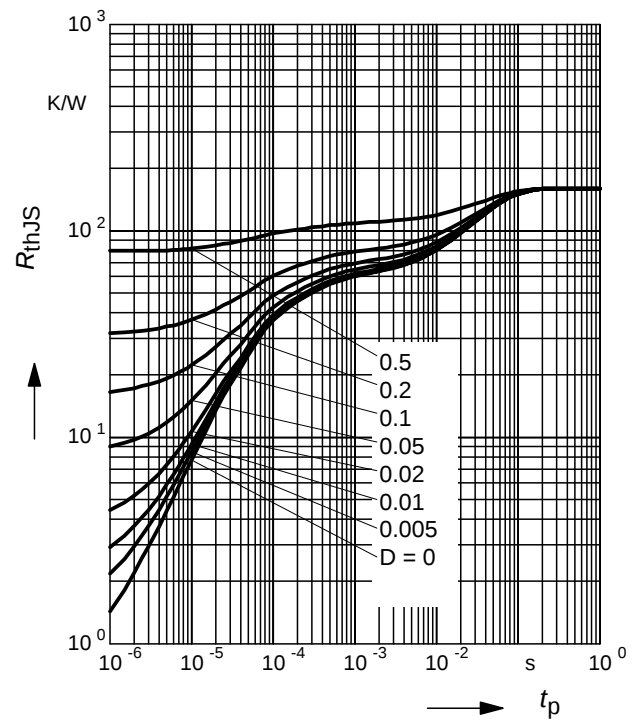
$$I_{Fmax}/I_{FDC} = f(t_p)$$

BAV99U



Permissible Puls Load $R_{thJS} = f(t_p)$

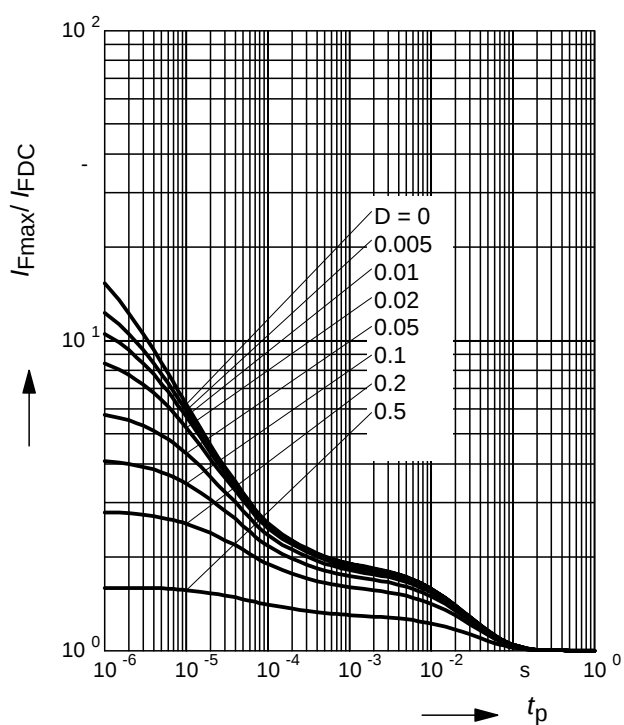
BAV99W



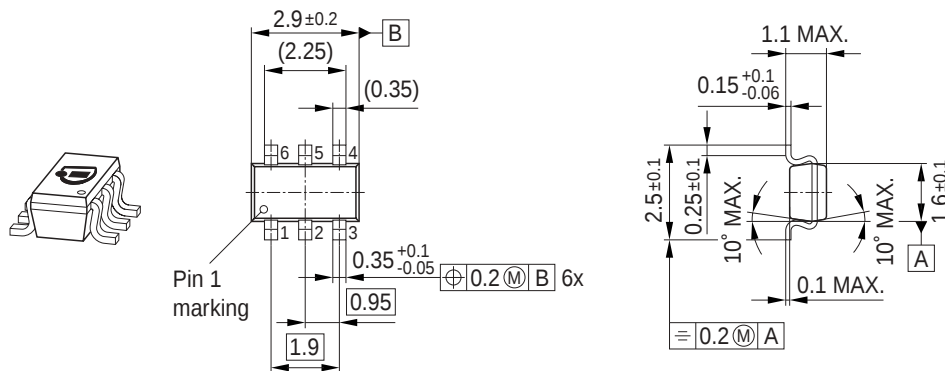
Permissible Pulse Load

$$I_{Fmax}/I_{FDC} = f(t_p)$$

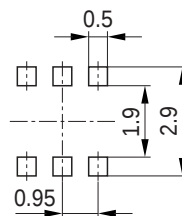
BAV99W



Package Outline

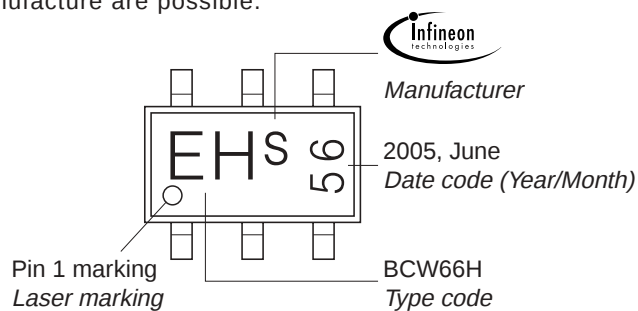


Foot Print



Marking Layout (Example)

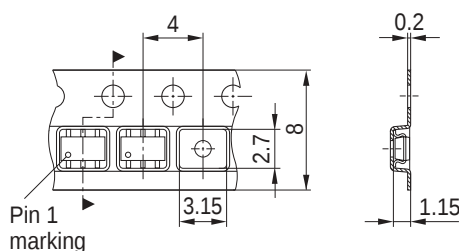
Small variations in positioning of Date code, Type code and Manufacture are possible.



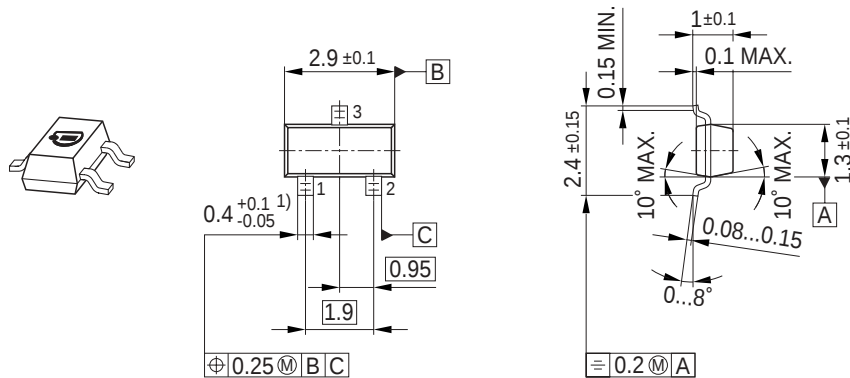
Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel
Reel ø330 mm = 10.000 Pieces/Reel

For symmetric types no defined Pin 1 orientation in reel.

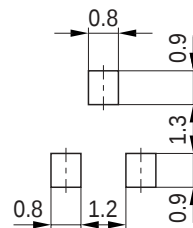


Package Outline

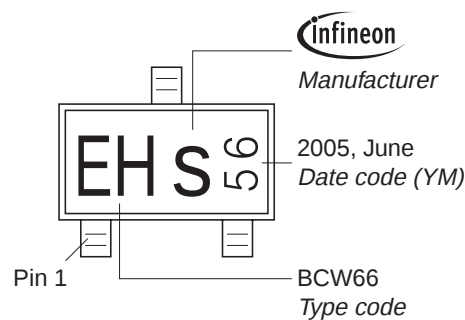


1) Lead width can be 0.6 max. in dambar area

Foot Print

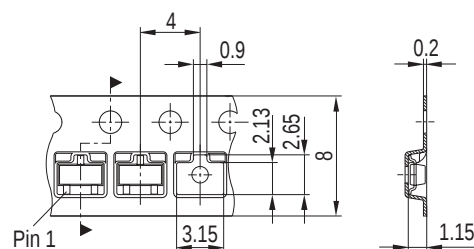


Marking Layout (Example)

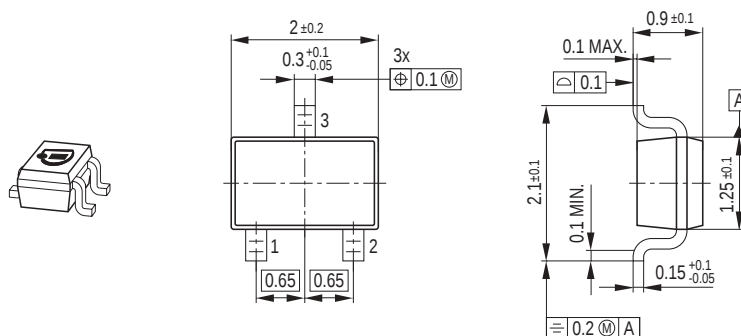


Standard Packing

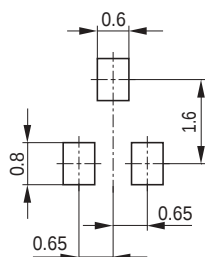
Reel $\varnothing 180 \text{ mm}$ = 3.000 Pieces/Reel
 Reel $\varnothing 330 \text{ mm}$ = 10.000 Pieces/Reel



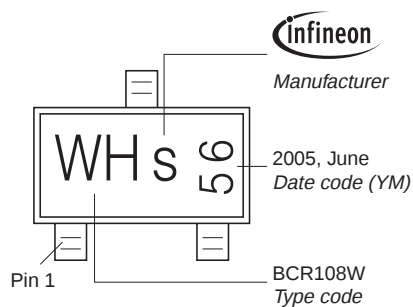
Package Outline



Foot Print

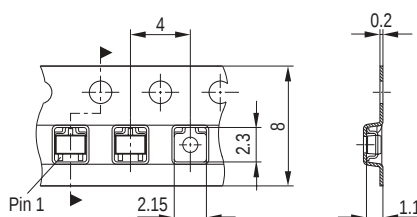


Marking Layout (Example)

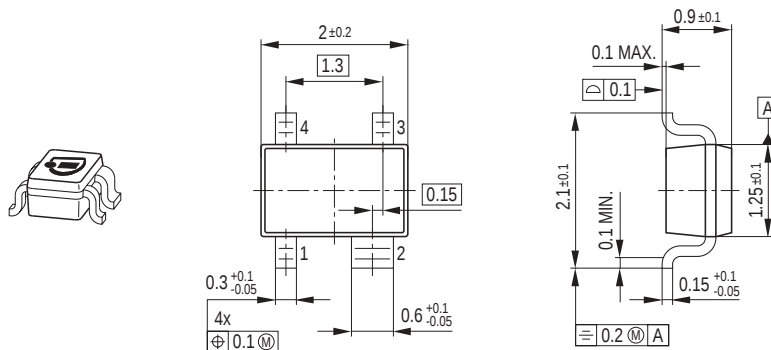


Standard Packing

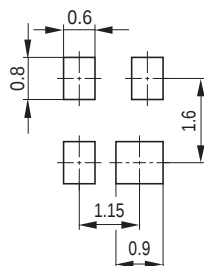
Reel $\varnothing 180$ mm = 3.000 Pieces/Reel
 Reel $\varnothing 330$ mm = 10.000 Pieces/Reel



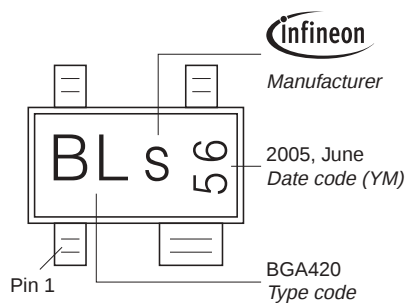
Package Outline



Foot Print

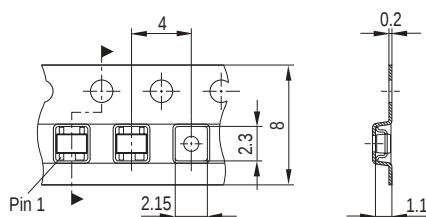


Marking Layout (Example)



Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel
 Reel ø330 mm = 10.000 Pieces/Reel



The drawing shows the mechanical specifications for the 6-pin connector. The top view (left) shows a rectangular component with six pins. The overall width is 2 ± 0.2 . The distance between the centerlines of the pins is $0.2^{+0.1}_{-0.05}$. The pins are numbered 1 through 6, with Pin 1 marking indicated. The distance between the centerlines of pins 1 and 2 is 0.65 , and between pins 2 and 3 is 0.65 . The distance between the centerlines of pins 4, 5, and 6 is 0.1 with a tolerance of 0.1 M . The side view (right) shows the profile of the component. The overall height is 0.9 ± 0.1 . The distance from the top surface to the centerline of the pins is 0.1 MAX. . The distance from the bottom surface to the centerline of the pins is 0.1 MIN. . The distance from the bottom surface to the centerline of the pins is 1.25 ± 0.1 . The distance from the bottom surface to the centerline of the pins is $0.15^{+0.1}_{-0.05}$. The distance from the bottom surface to the centerline of the pins is 0.2 M with a tolerance of 0.2 M and a tolerance of 0.2 M .

Infineon technologies

Manufacturer

2005, June

Date code (Year/Month)

Pin 1 marking

Laser marking

BCR108S

Type code

Technical drawing of a PCB layout for a 3-pin header. The top view shows a rectangular board with a width of 8mm and a length of 4mm. Three pins are spaced 2.15mm apart. A 'Pin 1' marking is shown. A side view shows the board thickness as 1.1mm and the pin height as 0.2mm.

Edition 2006-02-01

Published by

Infineon Technologies AG

81726 München, Germany

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